PATENT COOPERATION TREATY

From the INTERNATIONAL SEARCHING AUTHORITY		ANC.		
To:			PCT PTON	
<u>.</u>			RITTEN OPINION OF THE IONAL SEARCHING AUTHORITY	
· .			(PCT Rule 43bis.1)	
		Date of mailing (day/month/year)		
Applicant's or agent's file reference		FOR FURTHER	ACTION	
R00230WO01			See paragraph 2 below	
International application No. PCT/JP2005/000235	International filing date (day/month/year)	Priority date (day/month/year) 22.01.2004	
International Patent Classification (IPC) or be	The national classification and	d IPC		
indicational ratem Classification (If C) of bo				
Applicant	_			
Renesas Technology (Corp.			
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1 This animina contains in disease.	lating to the following items	••		
 This opinion contains indications re 		•		
Box No. I Basis of t	he opinion			
Box No. II Priority				
<u></u>	olishment of opinion with reg	gard to novelty, invent	ive step and industrial applicability	
<u> </u>	nity of invention			
	statement under Rule 43bis. ity; citations and explanation		novelty, inventive step or industrial tement	
Box No. VI Certain d	ocuments cited			
Box No. VII Certain d	efects in the international app	plication		
Box No. VIII Certain o	bservations on the internation	nal application		
2. FURTHER ACTION				
International Preliminary Examinia	ng Authority ("IPEA") except the chosen IPEA has notified	ot that this does not ap I the International Bur	Il be considered to be a written opinion of the ply where the applicant chooses an Authority other reau under Rule 66.1 bis(b) that written opinions of	
If this opinion is, as provided abouritten reply together, where app PCT/ISA/220 or before the expirat	ropriate, with amendments,	before the expiration	A, the applicant is invited to submit to the IPEA a of 3 months from the date of mailing of Form expires later.	
For further options, see Form PCT	TSA/220.			
3. For further details, see notes to For	m PCT/ISA/220.		•	
Name and mailing address of the ISA/JP		Authorized officer		
Facsimile No.		Telephone No.		

Во	x No. I	Basis of this opinion
1.		regard to the language, this opinion has been established on the basis of the international application in the language in which it was unless otherwise indicated under this item.
		This opinion has been established on the basis of a translation from the original language into the following language, which is the language of a translation furnished for the purposes of international search (under
2	-	Rule 12.3 and 23.1(b)).
2.		regard to any nucleotide and/or amino acid sequence disclosed in the international application and necessary to the claimed ation, this opinion has been established on the basis of:
	a.	type of material
		a sequence listing
		table(s) related to the sequence listing
	b.	format of material
		in written format
		in computer readable form
:	c.	time of filing/furnishing
		contained in the international application as filed.
		filed together with the international application in computer readable form.
		furnished subsequently to this Authority for the purposes of search.
3.		In addition, in the case that more than one version or copy of a sequence listing and/or table(s) relating thereto has been filed or furnished, the required statements that the information in the subsequent or additional copies is identical to that in the application as
		filed or does not go beyond the application as filed, as appropriate, were furnished.
4.	Addi	tional comments:
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Box No	. IV Lack of unity of invention
1.	In response to the invitation (Form PCT/ISA/206) to pay additional fees the applicant has:
	paid additional fees
	paid additional fees under protest
	not paid additional fees
2.	This Authority found that the requirement of unity of invention is not complied with and chose not to invite the applicant to pay additional fees.
3. T	his Authority considers that the requirement of unity of invention in accordance with Rules 13.1, 13.2 and 13.3 is
	complied with .
Σ	not complied with for the following reasons:
	The present international application includes four inventions that do not satisfy the requirement of unity of invention. Main invention: Claims 1-10, 13, 16 and 17 Second invention: Claims 11 and 19
	Third invention: Claim 12 Fourth invention: Claims 14 and 15
	Fifth invention: Claim 18
	Search was made considering that claim 1 is "the first described invention," and as a result, it was found that since the technical feature of the main invention is disclosed as the prior art in documents [JP, 2002-40095, A (NEC Corp.), 6 February, 2002 (06.02.02), JP, 5-259306, A (Fujitsu Ltd.), 8 October, 1993 (08.10.93), and JP, 11-17058, A (NEC Corp.), 22 January, 1999 (22.01.99)], it does not appear to be novel. Therefore, the technical feature of the main invention cannot be considered to be "a special technical feature" in the sense of the second sentence of PCT Rule 13.2. In the comparison between claims 11 and 19 (second invention) and the aforesaid prior art, "the special technical feature" of the second invention is a spacer exposed from an encapsulating member. In the comparison between claim 12 (third invention) and the aforesaid prior art, "the special technical feature" of the third invention is a structure in which wiring is partially exposed on the surface of the encapsulating member. In the comparison between claims 14 and 15 (fourth invention) and the aforesaid prior art, "the special technical feature" of the fourth invention is a structure in which the thickness of the encapsulating member is thin in the peripheral portions. In the comparison between claim 18 (fifth invention) and the aforesaid prior art, "the special technical feature" of the fifth invention is a structure in which (1) a main semiconductor device is disposed on a substrate and (2) a semiconductor package is disposed on the main semiconductor device. There is no technical relationship among these second to fifth inventions involving one or more of the same or corresponding special technical features.
4. C	onsequently, this opinion has been established in respect of the following parts of the international application:
, D	
	all parts the parts and the state of the st
	the parts relating to claims Nos.

International application No.
PCT/JP2005/000235

Box No. V Reasoned statement under Rule 43bis.1(a)(i) with regard to novelty, inventive step or industrial applicability; citations and explanations supporting such statement				
1.	Statement		·	
	Novelty (N)	Claims	3, 7, 10-12, 14-16, 18-19	YES
		Claims	1-2, 4-6, 8-9, 13, 17	_ · NO
	Inventive step (IS)	Claims	,	YES
		Claims	1-19	NO
	Industrial applicability (IA)	Claims	1-19	YES
		Claims		_ NO

2. Citations and explanations:

Document 1: JP, 2002-40095, A (NEC Corp.), 6 February, 2002 (06.02.02)

Document 2: JP, 5-259306, A (Fujitsu Ltd.), 8 October, 1993 (08.10.93)

Document 3: JP, 11-17058, A (NEC Corp.), 22 January, 1999 (22.01.99)

Document 4: JP, 2003-224234, A (Kyocera Corp.), 8 August, 2003 (08.08.03)

Document 5: JP, 9-181254, A (Fujitsu Ten Ltd.), 11 July, 1997 (11.07.97)

Document 6: JP, 2000-323623, A (Mitsubishi Electric Corp.), 24 November, 2000 (24.11.00)

Document 7: JP, 2003-273317, A (NEC Electronics Corp.), 26 September, 2003 (26.09.03)

The subject matters of claims 1, 2, 4-6, 8, 9, 13 and 17 do not appear to be novel in view of document 1 cited in the ISR. The subject matters of claims 1, 2, 4-6, 8, 9, 13 and 17 are disclosed in document 1.

The subject matters of claims 1, 2, 4-6, 8 and 9 do not appear to be novel in view of document 2 cited n the ISR. The subject matters of claims 1, 2, 4-6, 8 and 9 are disclosed in document 2.

The subject matters of claims 1, 2, 4 and 9 do not appear to be novel in view of document 3 cited in the ISR. The subject matters of claims 1, 2, 4 and 9 are disclosed in document 3.

The subject matters of claims 3, 7, 10 and 16 do not appear to involve an inventive step in view of document 1 cited in the ISR. A mounting substrate provided with two or more sets of terminals is a well-known technique. Furthermore, the disposition of terminals for external connection and terminals for testing is a mere matter of design variation. Moreover, laminating two or more semiconductor chips is usually employed. Still furthermore, using an encapsulating member for wrapping the outer edge portions of a substrate is a mere commonly used means.

The subject matters of claims 11 and 19 do not appear to involve an inventive step in view of documents 1 and 4 cited in the ISR. Disposing a spacer is described in document 4.

The subject matter of claim 12 does not appear to involve an inventive step in view of documents 1 and 5 cited in the ISR. Partially exposing wiring on the surface of an encapsulating member is described in document 5.

The subject matters of claims 14 and 15 do not appear to involve an inventive step in view of documents 1 and 6 cited in the ISR. Letting the encapsulating member have a relatively small thickness in the portion corresponding to the area where the terminals for external connection are disposed, is described in document 6. Furthermore, placing the said area in the outer circumferential

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portion i	s a mere matter of design variation.
documei substrate	The subject matter of claim 18 does not appear to involve an inventive step in view of ints 1 and 7 cited in the ISR. Disposing a main semiconductor on the surface of a main e and disposing a semiconductor package on the surface of the main semiconductor are d in document 7.
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	,

Supplemental box
In case the space in any of the preceding boxes is not sufficient. Continuation of:
IV.3.
Meanwhile, since the subject matters of claims 2-10, 13, 16 and 17 are mere additions of well-known techniques to the subject matter of claim 1, these claims are classified into the same group as claim 1.
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Applicant's or agent's file reference		FOR FURTHER A	ACTION
R00230WO01	•		See paragraph 2 below
International application No.	International filing date (dav/month/vear)	Priority date (day/month/year)
PCT/JP2005/000235	12.01.2005		22.01.2004
International Patent Classification (IPC) or both	national classification and	d IPC	
Applicant Renesas Technology Co	orp.		-
1. This opinion contains indications related	ling to the following items	:	
Box No. I Basis of the	opinion		
Box No. II Priority			
Box No. III Non-establis	shment of opinion with reg	gard to novelty, invent	ive step and industrial applicability
Box No. IV Lack of unit	y of invention		
	atement under Rule 43bis. c; citations and explanation		novelty, inventive step or industrial ement
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For further options, see Form PCT/IS	A/220.		
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Name and mailing address of the ICA/ID		Authorized officer	
Name and mailing address of the ISA/JP		Addroitzed Officer	
Facsimile No.		Telephone No.	•

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not complied with for the following reasons:
The present international application includes four inventions that do not satisfy the requirement of unity of invention. Main invention: Claims 1-10, 13, 16 and 17 Second invention: Claims 11 and 19 Third invention: Claim 12 Fourth invention: Claims 14 and 15 Fifth invention: Claim 18
Search was made considering that claim 1 is "the first described invention," and as a result, it was found that since the technical feature of the main invention is disclosed as the prior art in documents [JP, 2002-40095, A (NEC Corp.), 6 February, 2002 (06.02.02), JP, 5-259306, A (Fujitsu Ltd.), 8 October, 1993 (08.10.93), and JP, 11-17058, A (NEC Corp.), 22 January, 1999 (22.01.99)], it does not appear to be novel. Therefore, the technical feature of the main invention cannot be considered to be "a special technical feature" in the sense of the second sentence of PCT Rule 13.2. In the comparison between claims 11 and 19 (second invention) and the aforesaid prior art, "the special technical feature" of the second invention is a spacer exposed from an
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all parts
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International application No.
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Supplemental Box

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IV.3.		
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